

Product Change Notification - KSRA-30MKCM076

Date:

26 Jun 2018

Product Category:

Interface- Controller Area Network (CAN); Linear Op Amps; Power MOSFET Drivers; Switching Regulators; Memory

Affected CPNs:

7

Notification subject:

CCB 3269 Final Notice: Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Pre Change:

Using 8200T die attach material and G770HCD molding compound material

Post Change:

Using 8200T or 8600 die attach material and G770HCD or G700LTD molding compound material **Pre and Post Change Summary:**

| | Pre Change | Post Change | | | | | |
|---------------------------|-------------------|-------------------|-------------------|--|--|--|--|
| Assembly Site | UTAC Thai Limited | UTAC Thai Limited | UTAC Thai Limited | | | | |
| | LTD. / NSEB | LTD. / NSEB | LTD. / NSEB | | | | |
| Wire material | Au wire | Au wire | Au wire | | | | |
| Die attach material | 8200T | 8200T | 8600 | | | | |
| Molding compound material | G770HCD | G770HCD | G700LTD | | | | |
| Lead frame material | C194 | C194 | C194 | | | | |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying G770HCD mold compound and 8600 die attach material. **Change Implementation Status:**

In Progress

Estimated First Ship Date:

July 26, 2018 (date code: 1830)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:



| | January 2018 | | | | | June 2018 | | | | July 2018 | | | | | | |
|------------------------|--------------|----|----|----|----|------------------------------|--|----|----|-----------|----|----|----|----|----|----|
| Workweek | 01 | 02 | 03 | 04 | 05 | େ <mark>୮</mark> ୧୨ ୬ ଜ ଆ | | 23 | 24 | 25 | 26 | 27 | 28 | 29 | 30 | 31 |
| Initial PCN Issue Date | | | | Х | | | | | | | | | | | | |
| Qual Report | | | | | | | | | | | V | | | | | |
| Availability | | | | | | | | | | | ^ | | | | | |
| Final PCN Issue Date | | | | | | | | | | | Х | | | | | |
| Estimated | | | | | | | | | | | | | | | Х | |
| Implementation Date | | | | | | | | | | | | | | | | |

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report **Revision History:**

February 12, 2018: Issued initial notification.

June 26, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on July 26, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachment(s):

PCN_KSRA-30MKCM076_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

24AA00T-I/MNY 24AA128T-I/MNY 24AA256T-E/MNY 24AA256T-I/MNY 24C00T-E/MNY 24C00T-I/MNY 24FC128T-I/MNY 24FC256T-I/MNY 24LC00T-I/MNY 24LC128T-E/MNY 24LC128T-I/MNY 24LC256T-E/MNY 24LC256T-I/MNY MCP14A0153T-E/MNY MCP14A0154T-E/MNY MCP14A0155T-E/MNY MCP14A0453-E/MNY MCP14A0453T-E/MNY MCP14A0454-E/MNY MCP14A0454T-E/MNY MCP14A0455-E/MNY MCP14A0455T-E/MNY MCP14A0601T-E/MNY MCP14A0602T-E/MNY MCP16251T-I/MNY MCP16252T-I/MNY MCP16311T-E/MNY MCP16312T-E/MNY MCP16331T-E/MNY MCP1661T-E/MNY MCP1662T-E/MNY MCP1663T-E/MNY MCP1664T-E/MNY MCP2542FDT-E/MNY MCP2542FDT-H/MNY MCP2542WFDT-E/MNY MCP2542WFDT-H/MNY MCP2544FDT-E/MNY MCP2544FDT-H/MNY MCP2544WFDT-E/MNY MCP2544WFDT-H/MNY MCP2557FDT-H/MNY MCP2558FDT-H/MNY MCP621T-E/MNY MCP631T-E/MNY MCP651T-E/MNY

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MCP661T-E/MNY MCP6H01T-E/MNY MCP6H02T-E/MNY MCP6H71T-E/MNY MCP6H81T-E/MNY MCP6H82T-E/MNY MCP6H91T-E/MNY MCP6V01T-E/MNY MCP6V03T-E/MNY MCP6V06T-E/MNY MCP6V08T-E/MNY MCP6V26T-E/MNY